

## **AMENDMENTS TO THE ABSTRACT**

**Please amend the abstract as shown on the attached separate sheet, following the response.**

## ABSTRACT OF THE DISCLOSURE

There is provided a copper-plating liquid free from an alkali metal and a cyanide which, when used in plating of a substrate having an outer seed layer and fine recesses of a high aspect ratio, can reinforce the thin portion of the seed layer and can embed copper completely into the depth of the fine recesses. The plating liquid contains divalent copper ions and a complexing agent, and an optional pH adjusting agent.

~~———The plating liquid contains divalent copper ions and a complexing agent, and an optional pH adjusting agent.~~